- 1	

L	Hits	Search Text	DB	I m:
Number) DB	Time stamp
2	149359	sputter\$3	USPAT;	2002/11/06
			US-PGPUB; EPO; JPO; DERWENT;	10:06
9	21292	prevent adj contamination	IBM_TDB USPAT;	2002/11/06
	ļ		US-PGPUB;	2002/11/06
			EPO; JPO;	13.07
	ļ		DERWENT;	
16	1056	sputter\$3 and (prevent adj contamination)	IBM_TDB	2000/11/10
		and (aluminum or al)	USPAT; US-PGPUB;	2002/11/06
		,	EPO; JPO;	10.07
			DERWENT;	
23	25	sputter\$3 same (prevent adj	IBM_TDB	
		contamination) same (aluminum or al)	USPAT; US-PGPUB;	2002/11/06
		, and the same of all	EPO; JPO;	10:12
			DERWENT;	
30	5	(sputter\$3 with (aluminum or al)) and	IBM_TDB	
	Ĭ	((prevent adj contamination) same (coat\$3	USPAT;	2002/11/06
j		with (chamber or wall)))	US-PGPUB; EPO; JPO;	10:13
		,.,	DERWENT;	
			IBM TDB	

L	Hits	Search Text	DB	Time stamp
Number				•
2	35605	(wafer or substrate) with (pedestal or	USPAT;	2002/11/06
		lifter or holder)	US-PGPUB;	08:28
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
9	6205	(pin or support or finger) same ((wafer	USPAT;	2002/11/06
		or substrate) with (pedestal or lifter or	US-PGPUB;	08:29
		holder))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	1
16	10035	(self-centering) or (self adj centering)	USPAT;	2002/11/06
			US-PGPUB;	08:29
			EPO; JPO;	
			DERWENT;	
23	5	//nin or support or finger) some //wwfer	IBM_TDB	2002/11/06
23	5	((pin or support or finger) same ((wafer	USPAT;	2002/11/06
		or substrate) with (pedestal or lifter or	US-PGPUB;	08:29
		holder)))	EPO; JPO;	
		auj cencering//	DERWENT;	
			IBM_TDB	